ABSOCIATION CONNECTING ELECTRONICS INDUSTRIES® MALECTRONICS INDUSTRIES®	burn, Illinois. All right	ts reserved under both	This docume level parts, t	ent is a declaration en	n of the substance compasses all low	es within the manufactur ver level materials for wl	er listed item. No hich the manufac	ote: if the item is an a cturer has engineering	ssembly with lower responsibility.		
IPC Web Site for Information on http://www.ipc.org/IPC-175x	IPC Web Site for Information on IPC-1752 Standard Form Ty http://www.ipc.org/IPC-175x Distribut			Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information				rmation			
Supplier Information											
Company name*	any name* Company unique ID			Unique ID Authority			Response Date*				
onsemi								2025-06-06			
Contact Name	Title - Contact			Phone - Contact*			Email - Contact*				
Product-Env-Stewards	tewards Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*	horized Representative* Title - Representative			Phone - Representative*				Email - Representative*			
Product-Env-Stewards Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Requester Item Number Mfr Iter	n Number Mfr It	Mfr Item Name		Effective Date	Version	Manufacturing Site	Weight	.* UOM	Unit Type		
LM337.	BD2TR4G ANA	1.5A ADJ OUT NEG VI	REG	2025-06-06		MY1	909.21	mg	Each		
Manufacturing Proccess Information									·		
Terminal Plating / Grid Array Material	Ferminal Base Alloy	J-STD-020 M	ISL Rating	Peak Process Body Tempe		ture Max Time at Peak	Temperature N	Number of Reflow Cy	cles		
Matte Tin (Sn) - annealed CU Alloy 1		1		260	С	30	seconds 3	\$			
Comments											
level 1 - maximum time at peak temperature during s	Idering is 10-30 secon	nds									
For more information regarding material composition	please refer to page 3	3									

RoHS Material Composition Declaration				Declaration Type *	Detailed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).								
lease indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, admium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part normalies a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall accuracy and that such information is true and correct to the best of its knowledge and belief, so for the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Implement the row acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not idependently verified information provided by others, Supplier agrees that, at a minimum, itsuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the ertification in this paragraph. If the Company and the Supplier into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of arranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.									
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted				
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).						
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the				
Supplier Digital Signature	astislav Drska	Le							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.19	mg	Supplier	Silicon (Si)	7440-21-3		0.19	mg
Die Attach	11.31	mg	А	Lead (Pb)	7439-92-1	7a	10.7445	mg
			Supplier	Tin (Sn)	7440-31-5		0.5655	mg
Lead Frame 340	340.51	mg	Supplier	Iron (Fe)	7439-89-6		0.3405	mg
			Supplier	Copper (Cu)	7440-50-8		340.0674	mg
			Supplier	Phosphorus (P)	7723-14-0		0.1022	mg
Mold Compound-Black 5	529.31	mg		Epoxy resin	proprietary data		15.8793	mg
			Supplier	Phenolic Resin	Proprietary Data		7.9396	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		79.3965	mg
			Supplier	Carbon Black (C)	1333-86-4		2.6465	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		423.448	mg
Plating	27.15	mg	Supplier	Tin (Sn)	7440-31-5		27.15	mg
Wire Bond - Cu	0.74	mg	Supplier	Copper (Cu)	7440-50-8		0.74	mg